

### **General Description**

The MAX3385E is a 3V-powered EIA/TIA-232 and V.28/V.24 communications interface with low power requirements, high data-rate capabilities, and enhanced electrostatic discharge (ESD) protection. All transmitter outputs and receiver inputs are protected to ±15kV using IEC 1000-4-2 Air-Gap Discharge, ±8kV using IEC 1000-4-2 Contact Discharge, and ±15kV using the Human Body Model.

The transceiver has a proprietary low-dropout transmitter output stage, delivering true RS-232 performance from a +3.0V to +5.5V supply with a dual charge pump. The charge pump requires only four small 0.1µF capacitors for operation from a +3.3V supply. Each device is guaranteed to run at data rates of 250kbps while maintaining RS-232 output levels.

The MAX3385E has two receivers and two drivers. It features a 1µA shutdown mode that reduces power consumption and extends battery life in portable systems. Its receivers can remain active in shutdown mode, allowing external devices such as modems to be monitored using only 1µA supply current.

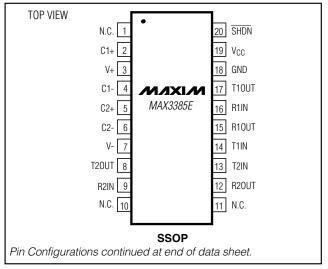
The MAX3385E is available in a space-saving SSOP package in either the commercial (0°C to +70°C) or extended-industrial (-40°C to +85°C) temperature range.

### **Applications**

Hand-Held Equipment Peripherals **Printers** 

Battery-Powered Equipment

#### **Pin Configurations**



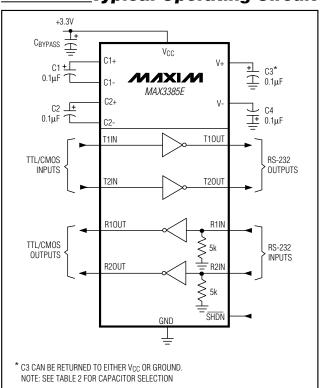
#### **Features**

- ♦ ESD Protection for RS-232 I/O Pins ±15kV—Human Body Model ±8kV—IEC 1000-4-2, Contact Discharge ±15kV—IEC 1000-4-2, Air-Gap Discharge
- ♦ Latchup Free
- ♦ 300µA Supply Current
- ◆ 1µA Low-Power Shutdown with Receivers Active
- ◆ 250kbps Guaranteed Data Rate
- ♦ 250µs Time to Exit Shutdown with 3kΩ Load on V+
- ♦ 6V/µs Guaranteed Slew Rate
- Meets EIA/TIA-232 Specifications Down to 3.0V

### **Ordering Information**

PART	TEMP. RANGE	PIN-PACKAGE
MAX3385ECAP	0°C to +70°C	20 SSOP
MAX3385ECWN	0°C to +70°C	18 SO
MAX3385EEAP	-40°C to +85°C	20 SSOP

### Typical Operating Circuit



†Covered by U.S. Patent numbers 4,636,930; 4,679,134; 4,777,577; 4,797,899; 4,809,152; 4,897,774; 4,999,761; and other patents pending.

MIXIM

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#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND0.3V to	) +6V
VCC 10 G1 12 0.0 V 10	
V+ to GND (Note 1)0.3V to	+7V
V- to GND (Note 1)+0.3V to	
V+ + IV-I (Note 1)	+13V
Input Voltages	
T_IN, SHDN to GND0.3V to	+6V
R_IN to GND	±25V
Output Voltages	
T_OUT to GND±	13.2V
R_OUT0.3V to (Vcc +	0.3V)
Short-Circuit Duration, T_OUT to GNDContin	

Continuous Power Dissipation (TA = +	70°C)
20-Pin SSOP (derate 8.00mW/°C abo	
18-Pin SO (derate 9.52mW/°C above	e +70°C)762mW
Operating Temperature Ranges	
MAX3385ECAP	0°C to +70°C
MAX3385ECWN	0°C to +70°C
MAX3385EEAP	40°C to +85°C
Storage Temperature Range	
Lead Temperature (soldering, 10sec).	+300°C

Note 1: V+ and V- can have maximum magnitudes of 7V, but their absolute difference cannot exceed 13V.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +3V \text{ to } +5.5V, C1-C4 = 0.1\mu\text{F, tested at } 3.3V \pm 10\%; C1 = 0.047\mu\text{F, } C2-C4 = 0.33\mu\text{F, tested at } 5.0V \pm 10\%; T_A = T_{MIN} \text{ to } T_{MAX, unless otherwise noted.}$  Typical values are at  $T_A = +25^{\circ}\text{C.})$ 

PARAMETER		CONDITIONS		TYP	MAX	UNITS
DC CHARACTERISTICS (VCC	$c = +3.3V \text{ or } +5V, T_A = +2$	25°C)	<u>"</u>			
Supply Current	SHDN = V <sub>CC</sub> , no loa	d		0.3	1	mA
Shutdown Supply Current	SHDN = GND	SHDN = GND		1	10	μΑ
LOGIC INPUTS			<u>'</u>			l.
Input Logic Threshold Low	T_IN, SHDN				0.8	V
lanut Lagia Thrashald High	T_IN, SHDN	$V_{CC} = 3.3V$	2.0			V
Input Logic Threshold High	ו_ווא, אוטוא	$V_{CC} = 5.0V$	2.4			V
Transmitter Input Hysteresis		<u>'</u>		0.5		V
Input Leakage Current	T_IN, SHDN			±0.01	±1	μΑ
RECEIVER OUTPUTS			<u> </u>			
Output Leakage Current	R_OUT, receivers dis	sabled		±0.05	±10	μΑ
Output Voltage Low	I <sub>OUT</sub> = 1.6mA				0.4	V
Output Voltage High	I <sub>OUT</sub> = -1.0mA		Vcc - 0.6	Vcc - 0.1		V
RECEIVER INPUTS						I.
Input Voltage Range			-25		+25	V
lancet Threehold Lave	T 050C	Vcc = 3.3V	0.6	1.2		V
Input Threshold Low	IA = +25°C	$T_A = +25^{\circ}C$ $V_{CC} = 5.0V$		1.5		V
Lance of Theoretical I I hade	T 0500	V <sub>CC</sub> = 3.3V		1.5	2.4	V
Input Threshold High	$T_A = +25^{\circ}C$	Vcc = 5.0V		1.8	2.4	V
Input Hysteresis		1		0.5		V
Input Resistance	T <sub>A</sub> = +25°C		3	5	7	kΩ

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = +3V \text{ to } +5.5V, C1-C4 = 0.1\mu\text{F}, \text{ tested at } 3.3V \pm 10\%; C1 = 0.047\mu\text{F}, C2-C4 = 0.33\mu\text{F}, \text{ tested at } 5.0V \pm 10\%; T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}\text{C}.)$ 

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
TRANSMITTER OUTPUTS					1
Output Voltage Swing	All transmitter outputs loaded with 3kΩ to ground	±5	±5.4		V
Output Resistance	V <sub>CC</sub> = V+ = V- = 0, transmitter output = ±2V	300	10M		Ω
Output Short-Circuit Current				±60	mA
Output Leakage Current	$V_{CC} = 0$ or 3V to 5.5V, $V_{OUT} = \pm 12V$ , transmitters disabled			±25	μΑ
ESD PROTECTION					
	Human Body Model		±15		
R_IN, T_OUT	IEC1000-4-2 Air Discharge		±15		kV
	IEC1000-4-2 Contact Discharge		±8		

#### **TIMING CHARACTERISTICS**

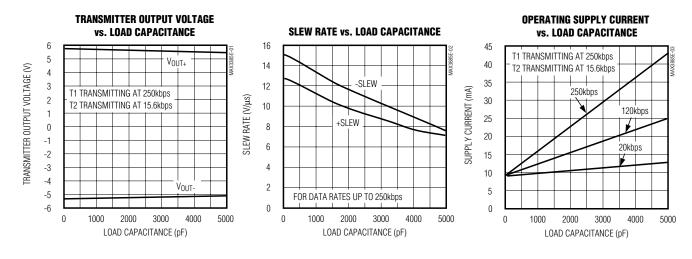
 $(V_{CC} = +3V \text{ to } +5.5V, C1-C4 = 0.1\mu\text{F, tested at } 3.3V \pm 10\%; C1 = 0.047\mu\text{F, } C2-C4 = 0.33\mu\text{F, tested at } 5.0V \pm 10\%; T_{A} = T_{MIN} \text{ to } T_{MAX, unless otherwise noted.}$ 

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Maximum Data Rate		$R_L = 3k\Omega$ , $C_L = 1000pF$ , one transmitter switching		250			kbps
Receiver Propagation Delay	t <sub>PHL</sub>	Receiver input to rec	Receiver input to receiver output,		0.15		μs
neceiver i ropagation belay	tplH	$C_L = 150pF$			0.15		μδ
Time to Exit Shutdown		$V_{OUT} \ge +3.7V$ , $R_{LOAD}$ at $V + = 3k\Omega$			250		μs
Transmitter Skew	Itphl - tplh I	(Note 2)			100		ns
Receiver Skew	Itphl - tplh I				50		ns
Transition-Region Slew Rate		$V_{CC} = 3.3V,$ $T_A = +25^{\circ}C,$ $R_L = 3k\Omega \text{ to } 7k\Omega.$	C <sub>L</sub> = 150pF to 1000pF	6		30	V/µs
Transition-negion siew hate		measured from +3V to -3V or -3V to +3V	$C_L = 150pF \text{ to}$ 2500pF	4		30	ν/μο

Note 2: Transmitter skew is measured at the transmitter zero cross points.

### **Typical Operating Characteristics**

 $(V_{CC} = +3.3V, 250 \text{kbps} \text{ data rate}, 0.1 \mu\text{F capacitors}, \text{ all transmitters loaded with } 3k\Omega \text{ and } C_L, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted.})$ 



### **Pin Description**

Р	PIN		FUNCTION		
so	SSOP	INAME	FUNCTION		
1	1, 10, 11	N.C.	No Connection. Not internally connected.		
2	2	C1+	Positive terminal of the voltage-doubler charge-pump capacitor.		
3	3	V+	+5.5V generated by the charge pump.		
4	4	C1-	Negative terminal of the voltage-doubler charge-pump capacitor.		
5	5	C2+	Positive terminal of inverting charge-pump capacitor.		
6	6	C2-	Negative terminal of inverting charge-pump capacitor.		
7	7	V-	-5.5V generated by the charge pump.		
8, 15	8, 17	T_OUT	RS-232 Transmitter Outputs		
9, 14	9, 16	R_IN	RS-232 Receiver Inputs		
10, 13	12, 15	R_OUT	TTL/CMOS Receiver Outputs		
11, 12	13, 14	T_IN	TTL/CMOS Transmitter Inputs		
16	18	GND	Ground		
17	19	Vcc	+3.0V to +5.5V Supply Voltage		
18	20	SHDN	Active-Low Shutdown-Control Input. Drive low to shut down transmitters and charge		

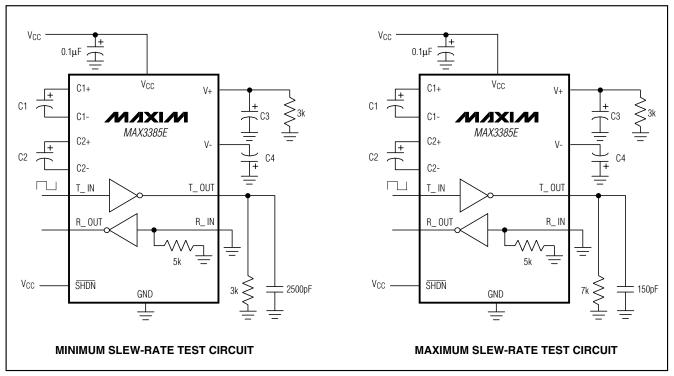


Figure 1. Slew-Rate Test Circuits

#### **Detailed Description**

#### **Dual Charge-Pump Voltage Converter**

The MAX3385E's internal power supply consists of a regulated dual charge pump that provides output voltages of +5.5V (doubling charge pump) and -5.5V (inverting charge pump), over the 3.0V to 5.5V VCC range. The charge pump operates in discontinuous mode; if the output voltages are less than 5.5V, the charge pump is enabled, and if the output voltages exceed 5.5V, the charge pump is disabled. Each charge pump requires a flying capacitor (C1, C2) and a reservoir capacitor (C3, C4) to generate the V+ and V-supplies (Figure 1).

#### **RS-232 Transmitters**

The transmitters are inverting level translators that convert CMOS-logic levels to ±5.0V EIA/TIA-232 levels.

The MAX3385E transmitters guarantee a 250kbps data rate with worst-case loads of  $3k\Omega$  in parallel with 1000pF, providing compatibility with PC-to-PC communication software (such as LapLink<sup>TM</sup>). Transmitters can be paralleled to drive multiple receivers or mice.

Laplink is a trademark of Traveling Software.

The MAX3385E's transmitters are disabled and the outputs are forced into a high-impedance state when the device is in shutdown ( $\overline{SHDN} = GND$ ). The MAX3385E permits the outputs to be driven up to  $\pm 12V$  in shutdown.

The transmitter inputs do not have pull-up resistors. Connect unused inputs to GND or VCC.

#### **RS-232 Receivers**

The receivers convert RS-232 signals to CMOS-logic output levels (Table 1).

#### **Shutdown Mode**

Supply current falls to less than  $1\mu A$  in shutdown mode (SHDN = low). When shut down, the device's charge pumps are shut off, V+ is pulled down to VCC, V- is pulled to ground, and the transmitter outputs are disabled (high impedance). The time required to exit shut-

**Table 1. Shutdown Truth Table** 

SHDN	T_OUT	R_OUT
0	High-Z	Active
1	Active	Active

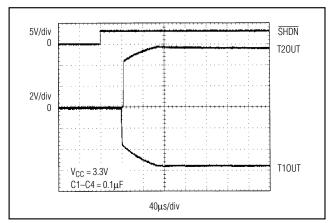


Figure 2. Transmitter Outputs Exiting Shutdown or Powering Up

down is typically 100 $\mu$ s, as shown in Figure 2. Connect SHDN to VCC if the shutdown mode is not used.

#### ±15kV ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against electrostatic discharges encountered during handling and assembly. The driver outputs and receiver inputs of the MAX3385E have extra protection against static electricity. Maxim's engineers have developed state-of-the-art structures to protect these pins against ESD of ±15kV without damage. The ESD structures withstand high ESD in all states: normal operation, shutdown, and powered down. After an ESD event, Maxim's "E" versions keep working without latchup, whereas competing RS-232 products can latch and must be powered down to remove latchup.

ESD protection can be tested in various ways; the transmitter outputs and receiver inputs of this product family are characterized for protection to the following limits:

- 1) ±15kV using the Human Body Model
- ±8kV using the contact-discharge method specified in IEC 1000-4-2
- 3) ±15kV using IEC 1000-4-2's air-gap method.

#### **ESD Test Conditions**

ESD performance depends on a variety of conditions. Contact Maxim for a reliability report that documents test setup, test methodology, and test results.

#### **Human Body Model**

Figure 3a shows the Human Body Model, and Figure 3b shows the current waveform it generates when dis-

charged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the test device through a 1.5k $\Omega$  resistor.

#### IEC 1000-4-2

The IEC 1000-4-2 standard covers ESD testing and performance of finished equipment; it does not specifically refer to integrated circuits. The MAX3385E helps you design equipment that meets Level 4 (the highest level) of IEC 1000-4-2, without the need for additional ESD-protection components.

The major difference between tests done using the Human Body Model and IEC 1000-4-2 is higher peak current in IEC 1000-4-2, because series resistance is lower in the IEC 1000-4-2 model. Hence, the ESD withstand voltage measured to IEC 1000-4-2 is generally lower than that measured using the Human Body Model. Figure 4a shows the IEC 1000-4-2 model, and Figure 4b shows the current waveform for the 8kV IEC 1000-4-2 Level 4 ESD contact-discharge test.

The air-gap test involves approaching the device with a charged probe. The contact-discharge method connects the probe to the device before the probe is energized.

#### Machine Model

The Machine Model for ESD tests all pins using a 200pF storage capacitor and zero discharge resistance. Its objective is to emulate the stress caused by contact that occurs with handling and assembly during manufacturing. Of course, all pins require this protection during manufacturing, not just RS-232 inputs and outputs. Therefore, after PC board assembly, the Machine Model is less relevant to I/O ports.

## **Applications Information**

#### **Capacitor Selection**

The capacitor type used for C1–C4 is not critical for proper operation; polarized or nonpolarized capacitors can be used. The charge pump requires 0.1µF capacitors for 3.3V operation. For other supply voltages, refer to Table 2 for required capacitor values. Do not use val-

Table 2. Required Minimum Capacitance Values

V <sub>CC</sub> (V)	C1, C <sub>BYPASS</sub> (µF)	C2, C3, C4 (μF)
3.0 to 3.6	0.1	0.1
4.5 to 5.5	0.047	0.33
3.0 to 5.5	0.1	0.47

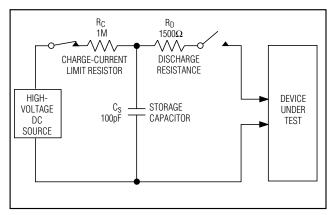


Figure 3a. Human Body ESD Test Model

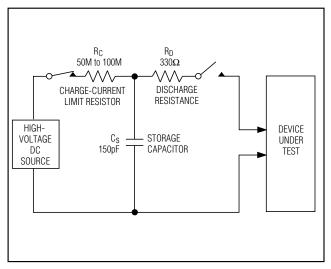


Figure 4a. IEC 1000-4-2 ESD Test Model

ues smaller than those listed in Table 2. Increasing the capacitor values (e.g., by a factor of 2) reduces ripple on the transmitter outputs and slightly reduces power consumption. C2, C3, and C4 can be increased without changing C1's value. However, do not increase C1 without also increasing the values of C2, C3, C4, and CBYPASS to maintain the proper ratios (C1 to the other capacitors).

When using the minimum required capacitor values, make sure the capacitor value does not degrade excessively with temperature. If in doubt, use capacitors with a larger nominal value. The capacitor's equivalent series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V-.

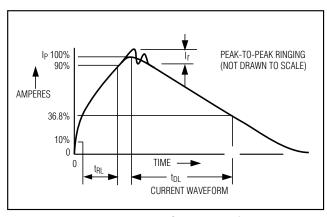


Figure 3b. Human Body Model Current Waveform

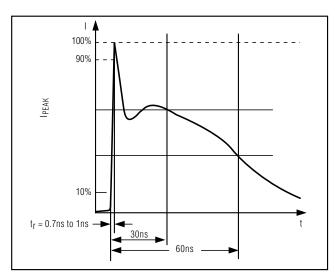


Figure 4b. IEC 10000-4-2 ESD Generator Current Waveform

#### **Power-Supply Decoupling**

In most circumstances, a  $0.1\mu F$  VCC bypass capacitor is adequate. In applications that are sensitive to power-supply noise, use a capacitor of the same value as charge-pump capacitor C1. Connect bypass capacitors as close to the IC as possible.

#### **Operation Down to 2.7V**

Transmitter outputs will meet EIA/TIA-562 levels of ±3.7V with supply voltages as low as 2.7V.

# Transmitter Outputs when Exiting Shutdown

Figure 2 shows two transmitter outputs when exiting shutdown mode. As they become active, the two transmitter outputs are shown going to opposite RS-232 lev-

els (one transmitter input is high, the other is low). Each transmitter is loaded with  $3k\Omega$  in parallel with 2500pF. The transmitter outputs display no ringing or undesirable transients as they come out of shutdown. Note that the transmitters are enabled only when the magnitude of V- exceeds approximately -3V.

#### **High Data Rates**

The MAX3385E maintains the RS-232 ±5.0V minimum transmitter output voltage even at high data rates. Figure 6 shows a transmitter loopback test circuit. Figure 7 shows a loopback test result at 120kbps, and

Figure 8 shows the same test at 250kbps. For Figure 7, all transmitters were driven simultaneously at 120kbps into RS-232 loads in parallel with 1000pF. For Figure 8, a single transmitter was driven at 250kbps, and all transmitters were loaded with an RS-232 receiver in parallel with 1000pF.

#### Interconnection with 3V and 5V Logic

The MAX3385E can directly interface with various 5V logic families, including ACT and HCT CMOS. See Table 3 for more information on possible combinations of interconnections.

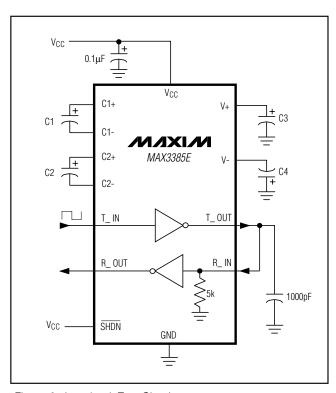


Figure 6. Loopback Test Circuit

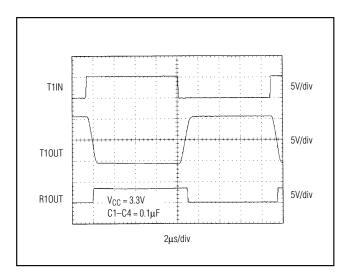


Figure 7. MAX3385E Loopback Test Result at 120kbps

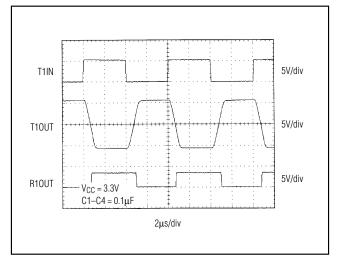
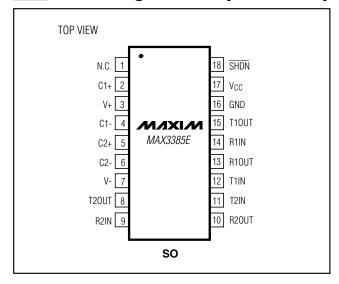


Figure 8. MAX3385E Loopback Test Result at 250kbps

Table 3. Logic-Family Compatibility with Various Supply Voltages

SYSTEM POWER-SUPPLY VOLTAGE (V)	V <sub>CC</sub> SUPPLY VOLTAGE (V)	COMPATIBILITY
3.3	3.3	Compatible with all CMOS families
5	5	Compatible with all TTL and CMOS families
5	3.3	Compatible with ACT and HCT CMOS, and with AC, HC, or CD4000 CMOS

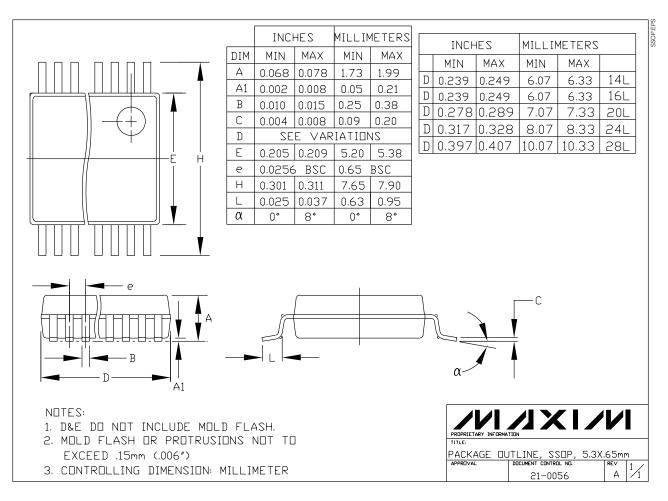
### Pin Configurations (continued)



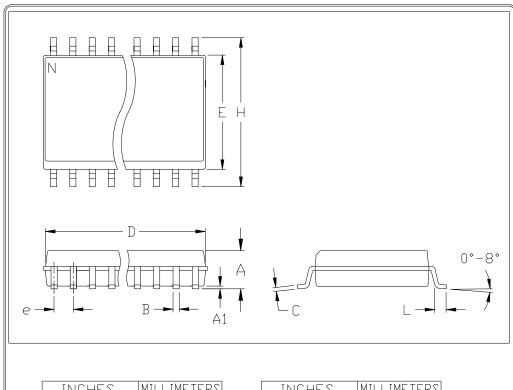
\_Chip Information

TRANSISTOR COUNT: 1129

### Package Information



### Package Information (continued)



	INCH	HF 2	MILLIM	IF LFK2
	MIN	MAX	MIN	MAX
А	0.093	0.104	2.35	2,65
Α1	0.004	0.012	0.10	0.30
В	0.014	0.019	0.35	0.49
С	0.009	0.013	0.23	0.32
6	0.0	50	1.	27
Ε	0.291	0.299	7.40	7.60
$\perp$	0.394	0.419	10.00	10.65
h	0.010	0.030	0.25	0.75
L	0.016	0.050	0.40	1.27

	INC	HES	MILLIM	1ETERS		
	MIN	MAX	MIN	MAX	Ν	MS013
D	0.398	0.413	10.10	10.50	16	AA
D	0.447	0.463	11.35	11.75	18	AB
D	0.496	0.512	12.60	13.00	20	AC
D	0.598	0.614	15.20	15.60	24	AD
D	0.697	0.713	17.70	18.10	28	AE

#### NOTES:

- 1. D&E DO NOT INCLUDE MOLD FLASH 2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED .15mm (.006")
- 3. LEADS TO BE COPLANAR WITHIN .102mm (.004")
- 4. CONTROLLING DIMENSION: MILLIMETER 5. MEETS JEDEC MS013-XX AS SHOWN
- IN ABOVE TABLE
- 6. N = NUMBER OF PINS

PACKAGE FAMILY DUTLINE: SDIC ,300"

21-0042 A

**NOTES** 

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.